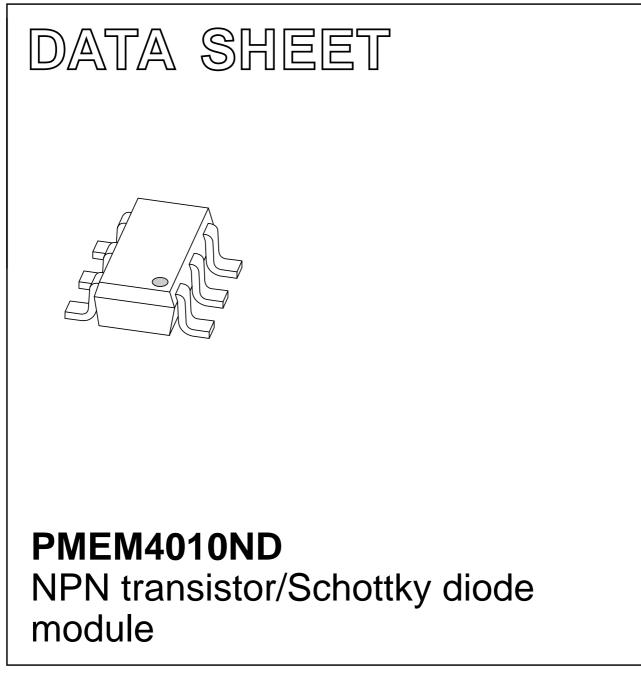
DISCRETE SEMICONDUCTORS



Product specification

2002 Oct 28



### FEATURES

- 600 mW total power dissipation
- High current capability
- Reduces required PCB area
- Reduced pick and place costs
- Small plastic SMD package.

#### Transistor:

• Low collector-emitter saturation voltage.

#### Diode:

- Ultra high-speed switching
- Very low forward voltage
- Guard ring protected.

### APPLICATIONS

- DC/DC convertors
- Inductive load drivers
- General purpose load drivers
- Reverse polarity protection circuits.

### DESCRIPTION

Combination of an NPN transistor with low  $V_{CEsat}$  and high current capability and a planar Schottky barrier diode with an integrated guard ring for stress protection in a SOT457 (SC-74) small plastic package.

PNP complement: PMEM4010PD.

### PINNING

PIN	DESCRIPTION	
1	emitter	
2	not connected	
3	cathode	
4	anode	
5	base	
6	collector	

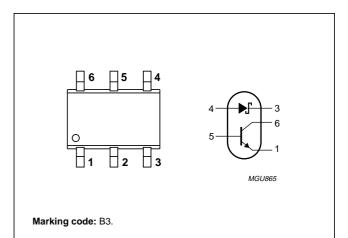


Fig.1 Simplified outline (SOT457) and symbol.

### PMEM4010ND

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### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
NPN trans	istor			-	
V <sub>CBO</sub>	collector-base voltage	open emitter	-	40	V
V <sub>CEO</sub>	collector-emitter voltage open base –		40	V	
V <sub>EBO</sub>	emitter-base voltage	open collector	_	5	V
l <sub>C</sub>	collector current (DC)		-	1	A
I <sub>CM</sub>	peak collector current		-	2	A
I <sub>BM</sub>	peak base current		-	1	A
Tj	junction temperature		-	150	°C
Schottky b	barrier diode	•		·	•
V <sub>R</sub>	continuous reverse voltage		_	20	V
l <sub>F</sub>	continuous forward current		-	1	A
I <sub>FSM</sub>	non repetitive peak forward current	t = 8.3 ms half sinewave; JEDEC method	-	5	A
Tj	junction temperature		_	125	°C
Combined	l device			•	
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$ ; note 1	-	600	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
T <sub>amb</sub>	operating ambient temperature -65			+125	°C

#### Note

1. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm<sup>2</sup>.

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R <sub>th j-a</sub>	thermal resistance from junction to ambient	in free air; note 1	208	K/W	

Note

1. Device mounted on a printed-circuit board; single sided copper; tinplated; mounting pad for collector 1 cm<sup>2</sup>.

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### CHARACTERISTICS

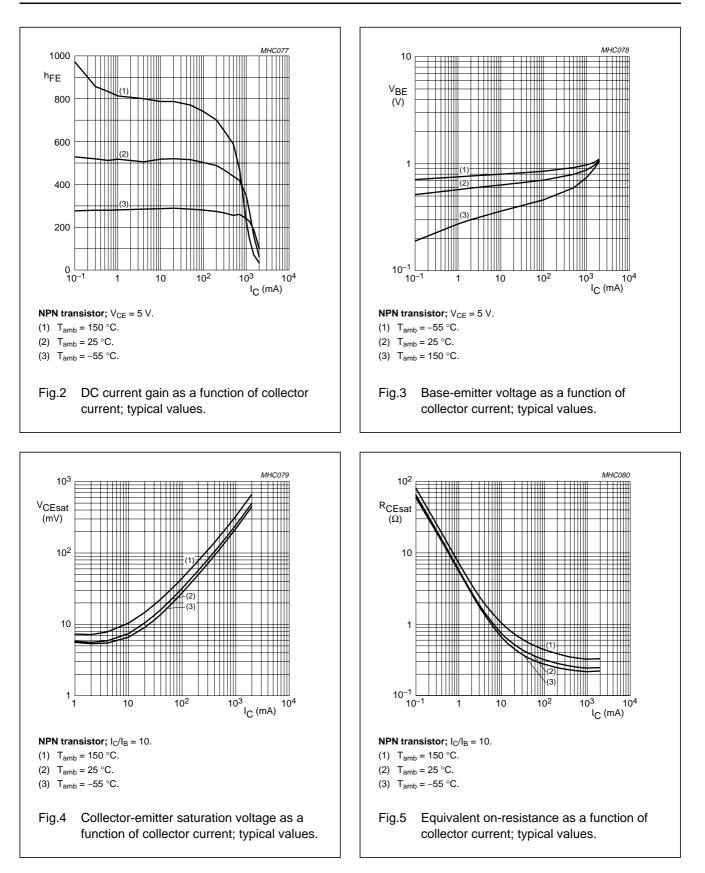
 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
NPN trans	istor	1		1	1	
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = 40 \text{ V}; I_E = 0$	-	-	100	nA
		$V_{CB} = 40 \text{ V}; I_E = 0; T_{amb} = 150 ^{\circ}\text{C}$	_	-	50	μA
I <sub>CEO</sub>	collector-emitter cut-off current	$V_{CE} = 30 \text{ V}; I_{B} = 0$	-	-	100	nA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; \text{ I}_{C} = 0$	_	-	100	nA
h <sub>FE</sub>	DC current gain	$V_{CE} = 5 \text{ V}; I_{C} = 1 \text{ mA}$	300	-	_	
		$V_{CE} = 5 \text{ V}; \text{ I}_{C} = 500 \text{ mA}$	300	-	900	
		$V_{CE} = 5 \text{ V}; \text{ I}_{C} = 1 \text{ A}$	200	-	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 100 mA; I <sub>B</sub> = 1 mA	_	-	80	mV
		I <sub>C</sub> = 500 mA; I <sub>B</sub> = 50 mA	_	-	110	mV
		I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA	-	-	190	mV
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA	-	-	1.2	V
R <sub>CEsat</sub>	equivalent on-resistance	I <sub>C</sub> = 500 mA; I <sub>B</sub> = 50 mA; note 1	-	260	<220	mΩ
V <sub>BEon</sub>	base-emitter turn-on voltage	$V_{CE} = 5 \text{ V}; \text{ I}_{C} = 1 \text{ A}$	-	-	1.1	V
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 50 mA; V <sub>CE</sub> = 10 V; f = 100 MHz	150	-	-	MHz
C <sub>c</sub>	collector capacitance	V <sub>CB</sub> = 10 V; I <sub>E</sub> = I <sub>e</sub> =0 ; f = 1 MHz	_	-	10	pF
Schottky I	barrier diode	•	•	•		•
V <sub>F</sub>	continuous forward voltage	I <sub>F</sub> = 10 mA; note 1	_	240	270	mV
		I <sub>F</sub> = 100 mA; note 1	_	300	350	mV
		I <sub>F</sub> = 1000 mA; see Fig.7; note 1	_	480	550	mV
I <sub>R</sub>	reverse current	$V_R = 5 V$ ; note 1	-	5	10	μA
		V <sub>R</sub> = 8 V; note 1	-	7	20	μA
		V <sub>R</sub> = 15 V; see Fig.8; note 1	-	10	50	μA
C <sub>d</sub>	diode capacitance	$V_R = 5 V$ ; f = 1 MHz; see Fig.9	-	19	25	pF

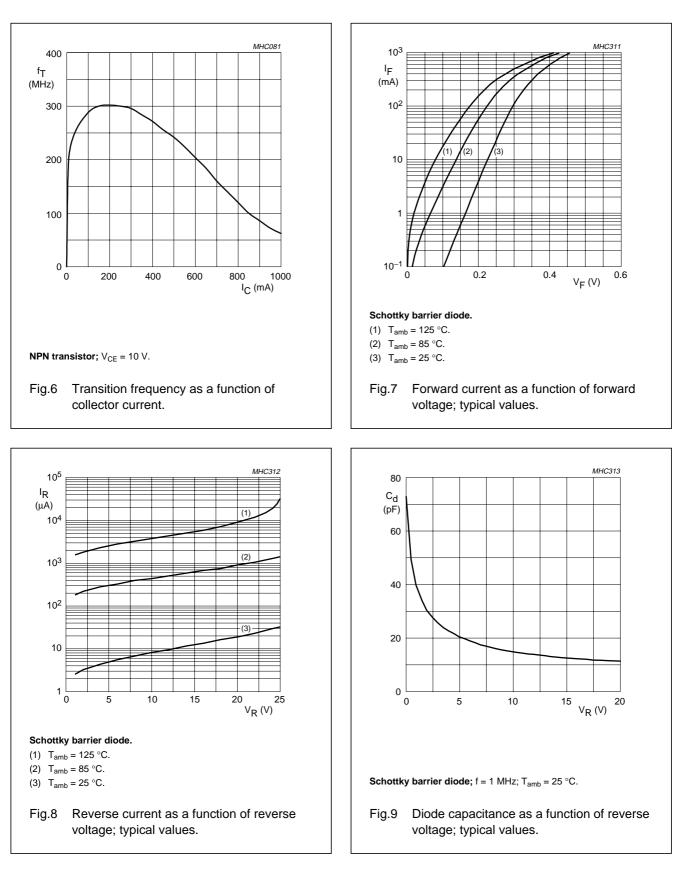
#### Note

1. Pulse test:  $t_p \leq 300 \ \mu s; \ \delta \leq 0.02.$ 

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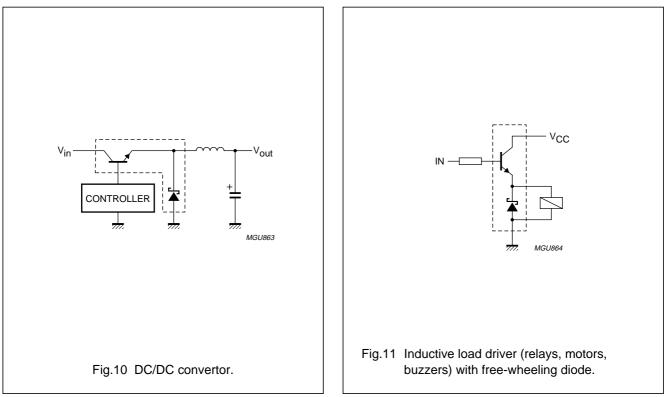


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### APPLICATION INFORMATION

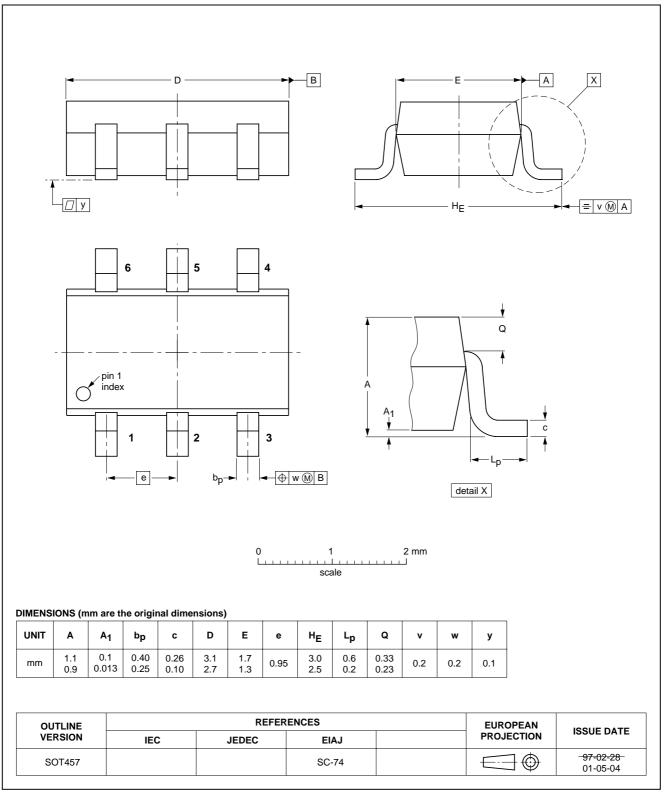


PMEM4010ND

## NPN transistor/Schottky diode module

### PACKAGE OUTLINE

### Plastic surface mounted package; 6 leads



# SOT457

### PMEM4010ND

#### DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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NOTES

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